

**IN THE SPECIFICATION**

Please amend the specification as follows:

**Page 1, line 1, please amend as follows:**

The invention relates to a method for completely or partly covering at least one electronic component with a compound, including the steps of:

placing the at least one electronic compound on a first mold half;  
completely or partly covering the electronic compound with the compound;  
moving a second mold half relative to the first mold half in the direction of the first mold half

~~according to the preamble of claim 1.~~

**Page 1, lines 2-3, please amend as follows:**

The invention also relates to an apparatus for carrying out the above method, having a first mold half and a second mold half, wherein the first mold half is moveable relative to the second mold half while an electronic component is received in a cavity defined by the mold halves

~~according to the preamble of claim 11.~~

**Page 1, lines 25-26, please amend as follows:**

To this end, the method ~~and apparatus described in the opening paragraph disclosed herein~~ are characterized provides that:

the distance between the two mold halves is regulated and adjusted while the two mold halves are moved towards each other and while the two mold halves are held in a position after having been moved towards each other during curing of the compound.

The apparatus disclosed herein is characterized in that the first mold half is provided with at least one actuator with the aid of which the position of the first mold half relative to the second mold half is accurately regulated, the apparatus being provided with a controller for regulating the positions of the at least one actuator, so that

the distance between the two mold halves is regulated and adjusted while the two mold halves are moved towards each other and while the two mold halves are held in a position after having been moved towards each other

~~by the features of claims 1 and 11, respectively.~~